

## EU Silicon Wafer Committee Meeting Summary and Minutes

SEMICON Europa 2012  
October 11, 2012  
Dresden, Germany

**Next Committee Meeting**  
SEMICON Europa 2013

### Table 1 Meeting Attendees

**Co-Chairs:** Frank Riedel (Siltronic), Peter Wagner (Self)

**SEMI Staff:** James Amano

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
SUMCO	Nakai	Tetsuo			
Shimzu Consulting (via phone)	Shimizu	Yasuhiro			

### Table 2 Leadership Changes

<i>Group</i>	<i>Previous Leader</i>	<i>New Leader</i>
EU Silicon Wafer Committee		Dr. Friedrich Passek (Siltronic)
International Polished Wafer Task Force		Dr. Frank Riedel (Siltronic)

### Table 3 Ballot Results

**Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

**Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting.

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
5430	Revision to SEMI M73-0309, Test Methods for Extracting Relevant Characteristics from Measured Wafer Edge Profiles	<b>Failed</b>

### Table 4 Authorized Ballots

<i>#</i>	<i>When</i>	<i>SC/TF/WG</i>	<i>Details</i>
5430A	Cycle 1-2013	International Advanced Wafer Geometry Task Force	Revision to SEMI M73-0309, Test Methods for Extracting Relevant Characteristics from Measured Wafer Edge Profiles
5500	Cycle 3-2013, 4-2013, or 5-2013	Intl. Polished Wafer TF	New Standard Specification for Polished Single Crystal Silicon Wafers for GaN-on-Silicon Applications

### Table 5 Authorized Activities

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
5500	SNARF	Intl. Polished Wafer TF	New Standard Specification for Polished Single Crystal Silicon Wafers for GaN-on-Silicon Applications

Note: SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

**Table 6 New Action Items**

None

**Table 7 Previous Meeting Action Items**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
EUSW-1110-01	Kevin Nguyen (SEMI)	To remove John Stover from the organization chart on ASI TF <b>CLOSED</b>
EUSW-1110-02	Kevin Nguyen (SEMI)	Kevin Nguyen to contact leaders of both doc. 5070 and 5071 and ask them to coordinate the effort. <ul style="list-style-type: none"> <li>• Doc. 5070, Revision to SEMI M76-0710, Specification for Developmental 450 mm Diameter Polished Single Crystal Silicon Wafers (Re: Edge Shape Design)</li> <li>• Doc. 5071, Revision to M76, Specification for developmental 450 mm diameter polished single crystal silicon wafers (Re: wafer back surface contamination and defectivity requirements.) <b>CLOSED</b></li> </ul>

## 1 Welcome, Reminders, and Introductions

Peter Wagner called the meeting to order at 10:15. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

## 2 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting.

**Motion:** To approve the minutes from the previous EU Silicon Wafer TC meeting (October 20,2010) as written.  
**By / 2<sup>nd</sup>:** Tetsuo Nakai (SUMCO)/Frank Riedel (Siltronic)  
**Discussion:** None  
**Vote:** 2-0

## 3 Liaison Reports

### 3.1 Japan Silicon Wafer Committee

Tetsuo Nakai (SUMCO ) reported. Most notably, JEITA is shutting down their Silicon Technology Committee at the end of 2012. A new JEITA “Transfer” Committee will evaluate existing JEITA Standards, and determine their suitability for potential transfer to SEMI, similar to what was previously done with a number of ASTM standards.

**Attachment:** JP\_SiW\_EU SE2012\_R1.0a.ppt

### 3.2 NA Silicon Wafer Committee

James Amano reported. Of note:

- New SNARFs
- SEMI M74-1108, Specification for 450 mm Diameter Mechanical Handling Polished Wafers, is due for 5 year review.
  - Ballot was issued in cycle 5-2012 as reapproval ballot doc. 5442 for adjudication at SEMICON Japan

**Attachment:** NA Si Wafer Liaison Report 2012September.ppt

### 3.3 SEMI Staff Report

James Amano reported.

- Critical dates for the first three cycles of 2013 have been set and can be found online at [semi.org/standards](http://semi.org/standards) and also in the attached report.
- The Silicon Wafer TC has been effectively maintaining its catalog of standards via five-year reapproval ballots.

**Attachment:** SEMI Staff Report SEMICON Europa Oct 2012 v2.ppt

## 4 Ballot Review

4.1 Document # 5430, Revision to SEMI M73-0309, Test Methods for Extracting Relevant Characteristics from Measured Wafer Edge Profiles

**Motion:** To find Masanori Yoshise's negative related and persuasive.

**By / 2<sup>nd</sup>:** Peter Wagner/Frank Riedel

**Discussion:** None

**Vote:** 2-0

**Motion:** To rebalot 5430 in Cycle 1-2013, for adjudication at SEMICON West

**By / 2<sup>nd</sup>:** Peter Wagner/Frank Riedel

**Discussion:** None

**Vote:** 2-0

## 5 Old Business

None.

## 6 New Business

6.1 SNARF for New Standard: Specification for Polished Single Crystal Silicon Wafers for GaN-on-Silicon Applications

- Frank Riedel presented the proposal. Gallium nitride on silicon wafers represent emerging markets with applications such as LED or high-frequency power devices. At present, the specifications for silicon wafer substrates requested by customers of such wafers differ widely. This new specification aims at unifying these silicon wafer specifications. Unification of specifications will be of great benefit for the entire related industry, which represents a huge future market. Work will take place in the International Polished Wafers Task Force

**Motion:** To approve the SNARF for New Standard: Specification for Polished Single Crystal Silicon Wafers for GaN-on-Silicon Applications

**By / 2<sup>nd</sup>:** Frank Riedel/Tetsuo Nakai

**Discussion:** None

**Vote:** 2-0

6.2 New leader for International Polished Wafer Task Force

**Motion:** To approve Frank Riedel as the leader of the International Polished Wafer Task Force

**By / 2<sup>nd</sup>:** Peter Wagner/Tetsuo Nakai

**Discussion:** None

**Vote:** 2-0

## 7 Action Item Review

### 7.1 Open Action Items

James Amano (SEMI) reviewed the open action items. These can be found in the Open Action Items table at the beginning of these minutes.

### 7.2 New Action Items

James Amano (SEMI) reviewed the new action items. These can be found in the New Action Items table at the beginning of these minutes.

## 8 Next Meeting and Adjournment

The next meeting of the EU Silicon Wafer committee is scheduled for October, 2013 in Dresden, Germany, during SEMICON Europa.

Minutes submitted by:

James Amano  
SEMI HQ

**Table 8 Index of Available Attachments** <sup>#1</sup>

#	Title	#	Title
	JP_SiW_EU SE2012_R1.0a.ppt		
	NA Si Wafer Liaison Report 2012September.ppt		

<sup>#1</sup> Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at [www.semi.org](http://www.semi.org).